



Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A printed circuit board comprising:

a first wiring layer on which a first conductive wiring is formed;

a second wiring layer on which a second conductive wiring is formed, wherein the first and second wiring layers are electrically non-conductive, and sides of the first and second wiring layers on which the first and second conductive wirings are respectively formed do not face each other;

a first conductive layer and a second conductive layer forming conductive regions are respectively laminated, with an insulating layer intervened therebetween, between the first wiring layer and the second wiring layer;

a conductive first interlayer connecting member that connects the first conductive wiring of the first wiring layer and the second conductive wiring of the second wiring layer; and

a conductive second interlayer connecting member that is connected to the conductive regions of the first conductive layer and the second conductive layer, is isolated from the first interlayer connecting member and surrounds the first interlayer connecting member.

wherein the first conductive layer and the second conductive layer respectively include plural conductive regions of different potentials, with the second interlayer connecting member connecting conductive regions of substantially the same potential of the first conductive layer and the second conductive layer.

2. (Canceled)

3. (Currently Amended) The printed circuit board of ~~claim 2~~, claim 1, wherein the plural conductive regions include a power region and a ground region.

4. (Currently Amended) ~~The~~ A printed circuit board of ~~claim 1~~, comprising:
a first wiring layer on which a first conductive wiring is formed;
a second wiring layer on which a second conductive wiring is formed, wherein
the first and second wiring layers are electrically non-conductive, and sides of the first and
second wiring layers on which the first and second conductive wirings are respectively
formed do not face each other;
a first conductive layer and a second conductive layer forming conductive
regions are respectively laminated, with an insulating layer intervened therebetween, between
the first wiring layer and the second wiring layer;
a conductive first interlayer connecting member that connects the first
conductive wiring of the first wiring layer and the second conductive wiring of the second
wiring layer; and
a conductive second interlayer connecting member that is connected to the
conductive regions of the first conductive layer and the second conductive layer, is isolated
from the first interlayer connecting member and surrounds the first interlayer connecting
member,
wherein the characteristic impedance relating to the first interlayer connecting
member and the second interlayer connecting member, the characteristic impedances of the
first wiring and the characteristic impedances of the second wiring are substantially identical.

5. (Original) The printed circuit board of claim 4, wherein at least one of an outer diameter of the first interlayer connecting member and an inner diameter of the second interlayer connecting member is adjusted so that the characteristic impedance relating to the first interlayer connecting member and the second interlayer connecting member, the

characteristic impedances of the first wiring and the characteristic impedances of the second wiring become substantially identical.

6. (Original) The printed circuit board of claim 4, further including a dielectric member between the first interlayer connecting member and the second interlayer connecting member, wherein the dielectric constant of the dielectric member is adjusted so that the characteristic impedance relating to the first interlayer connecting member and the second interlayer connecting member, the characteristic impedances of the first wiring and the characteristic impedances of the second wiring become substantially identical.

7. (Previously Presented) The printed circuit board of claim 1, wherein the first conductive wiring and the second conductive wiring are signal wires for signal transmission.

8. (Previously Presented) The printed circuit board of claim 1, wherein the first conductive wiring and the second conductive wiring are power wires for power supply.

9. (Previously Presented) The printed circuit board of claim 8, wherein a power terminal of an active device is connected to one of the first conductive wiring and the second conductive wiring, one end of a condenser is connected to the other of the first conductive wiring and the second conductive wiring, and the other end of the condenser is connected to a ground region disposed on at least one of the first conductive layer and the second conductive layer via third interlayer connecting member.

10. (Original) The printed circuit board of claim 8, wherein the dielectric constant between the first interlayer connecting member and the second interlayer connecting member is higher than the dielectric constant between the first conductive layer and the second conductive layer.

11. (Previously Presented) The printed circuit board of claim 1, further comprising a pair of the first interlayer connecting members, wherein the first conductive wiring is configured by a pair of first differential signal wirings for differential signals, the

second conductive wiring is configured by a pair of second differential signal wirings for the differential signals, and the pair of the first interlayer connecting members respectively connecting one of the pair of first differential signal wirings with one of the pair of second differential signal wirings and the other of the pair of first differential signal wirings with the other of the pair of second differential signal wirings is surrounded by the second interlayer connecting member.

12. (Original) The printed circuit board of claim 11, wherein the differential impedances of the first interlayer connecting members are substantially identical to the differential impedances of the first differential signal wirings and the second differential signal wirings.

13. (Original) The printed circuit board of claim 11, wherein the common mode impedances of the pair of first interlayer connecting member with respect to the ground regions of the first conductive layer and the second conductive layer are substantially identical to at least one of the common mode impedances of the pair of first differential signal wirings with respect to the ground regions and the common mode impedances of the pair of second differential signal wirings with respect to the ground regions.

14. (Original) The printed circuit board of claim 8, further including a dielectric member between the first interlayer connecting member and the second interlayer connecting member, wherein the dielectric constant of the dielectric member is adjusted so that the characteristic impedance relating to the first interlayer connecting member and the second interlayer connecting member and the characteristic impedance relating to the wirings become substantially identical.

15. (Original) The printed circuit board of claim 9, further including a dielectric member between the first interlayer connecting member and the second interlayer connecting member, wherein the dielectric constant of the dielectric member is adjusted so that the

characteristic impedance relating to the first interlayer connecting member and the second interlayer connecting member and the characteristic impedance relating to the wirings become substantially identical.

16. (Original) The printed circuit board of claim 1, wherein the second interlayer connecting member is formed by plural via holes.

17. (Previously Presented) A printed circuit board where a wiring layer for forming a conductive wiring and a first conductive layer and a second conductive layer forming conductive regions are respectively laminated with an insulating layer intervened therebetween, the printed circuit board comprising:

a conductive first interlayer connecting member that is connected to the wiring of the wiring layer; and

a conductive second interlayer connecting member that is connected to the conductive regions of the first conductive layer and the second conductive layer, is isolated from the first interlayer connecting member and surrounds the first interlayer connecting member, wherein

the first conductive layer and the second conductive layer respectively include plural conductive regions of different potentials, with the second interlayer connecting member connecting conductive regions of substantially the same potential of the first conductive layer and the second conductive layer.

18. (Previously Presented) The printed circuit board of claim 17, wherein a characteristic impedance of the first interlayer connecting member and the second interlayer connecting member is predetermined.

19. (Canceled)

20. (Currently Amended) The printed circuit board of ~~claim 19~~, claim 18, wherein the plural conductive regions include a power region and a ground region.